Unit 4 - Week 2:

Week 2 Assignment 2

The due date for submitting this assignment has passed. As per our records you have not submitted this assignment.

Due on 2019-02-13, 23:59 IST.

1) What is a primary function of chip carrier?
   - Interconnection from the Si microchip to the motherboard
   - Protection from abusive handling
   - Facilitate heat dissipation
   - All of the above

No, the answer is incorrect.
Score: 0
Accepted Answers:
   d.

2) How is the number of circuits/bits on a chip related to the number of interconnection:
   - Equal in number
   - Moore’s Law
   - Rent’s Rule
   - Arrhenius Law

No, the answer is incorrect.
Score: 0
Accepted Answers:
   d.
Where is a ceramic casing used in first level packaging?

- a. Military applications
- b. Power Electronics
- c. Consumer appliances
- d. Portable electronics

No, the answer is incorrect.
Score: 0
Accepted Answers:
- a.

4)
Which of the following is NOT a step in plastic encapsulation module assembly process?

- a. Wire bonding
- b. Die attach
- c. Solder bumping
- d. Marking

No, the answer is incorrect.
Score: 0
Accepted Answers:
- c.

5) What is a disadvantage of DIP?

- a. Limited number of interconnections
- b. Low reliability
- c. Expensive
- d. Low mechanical strength of pins

No, the answer is incorrect.
Score: 0
Accepted Answers:
- a.

6)
What type of leads do you find in a standard memory module?
- a. Pin in hole
- b. J-type
- c. Gull wing type
- d. Leadless

No, the answer is incorrect.
Score: 0
Accepted Answers:
- c.

Which of the following packages is removable?
- a. Ball Grid Array
- b. Pin Grid Array
- c. Quad Flat Pack
- d. Chip scale package

No, the answer is incorrect.
Score: 0
Accepted Answers:
- b.

In an LGA, what is the loading mechanism?
- a. Tensile load
- b. Compressed spring action
- c. Shear stress
- d. No loading is required

No, the answer is incorrect.
Score: 0
Accepted Answers:
- b.

9)
What is an advantage of LGA over PGA?

- a. Thinner package
- b. Lesser electrical paths
- c. Better signal integrity
- d. All of the above

No, the answer is incorrect.
Score: 0
Accepted Answers:
d.

What is the typical packaging efficiency of CSP?

- a. 2.0 - 2.5
- b. 0.5 – 1.0
- c. 1.0-1.2
- d. 1.0

No, the answer is incorrect.
Score: 0
Accepted Answers:
c.